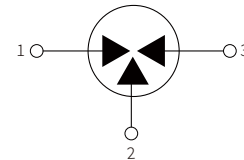


## FEATURES

- | Size Design  $\Phi 6.0 \times 8.5\text{mm}$
- | High Current Handling Capability 10,000A @ 8/20  $\mu\text{s}$
- | Low Capacitance and Insertion Loss
- | Quick Response and Long Service Life
- | Moisture sensitivity level: Level 1




 $\Phi 6.0 \times 8.5\text{mm}$ 


Schematic Symbol

## APPLICATION INFORMATION

- | Communication equipment.
- | Repeaters, Modems
- | Telephone Interface, Line cards.
- | Data communication equipment.

## AGENCY APPROVALS

Icon	Solderability
RoHS	Compliance with 2011/65/EU
HF	Compliance with IEC61249-2-21:2003
	Mean lead free
	UL Certificated E505857

## PRODUCT CHARACTERISTICS

Lead Material	Body Material	Terminal Finish
Copper or Fe-Ni alloy	Ceramics	100% Matte-Tin Plated

## ELECTRICAL PARAMETER

Parameter	Symbol	Rating	Unit
DC Blocking Voltage 1)2)	100V/s	480-720	V
Impulse Spark-over Voltage	At 1kV/ $\mu$ s	for 99 % of measured values $\leq$ 700	V
	At 1kV/ $\mu$ s	Typical values of distribution $\leq$ 650	V
Impulse Discharge Current 3)	8/20 $\mu$ s	20	KA
Insulation Resistance	DC=100V	$\geq$ 1	G $\Omega$
Capacitance at 1MHz	V <sub>DC</sub> =0.5V	$\leq$ 1.5	pF
Weight		~1.25	g
Operating and Storage Temperature		-40~125	$^{\circ}$ C

1) At delivery AQL 0.65 level II SO2859

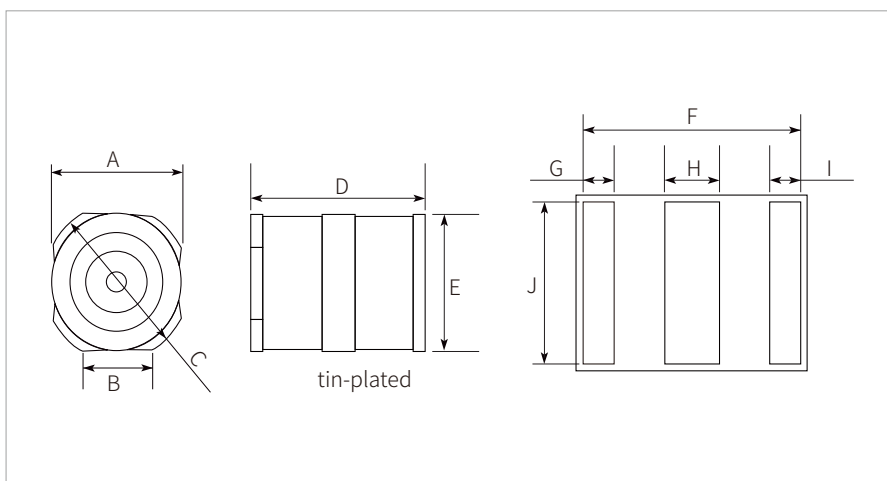
2) In ionized mode

3) Terms and waveforms in accordance with ITU-T Rec. K. 12; IIEC 61643-311

## ENVIRONMENTAL RELIABILITY CHARACTERISTICS

Testing items	Technical standards
High Temperature Storage Test	Temperature: 85 $^{\circ}$ C ; Time:2H
Low Temperature Storage Test	Temperature: -40 $^{\circ}$ C ; Time:2H
Vibration	Frequency: 10-500Hz ; Amplitude:0.15mm ; Time:45min
Resistance of soldering heat	Temperature: 260 $^{\circ}$ C; Time of dip soldering:10s,1time

## PRODUCT DIMENSIONS



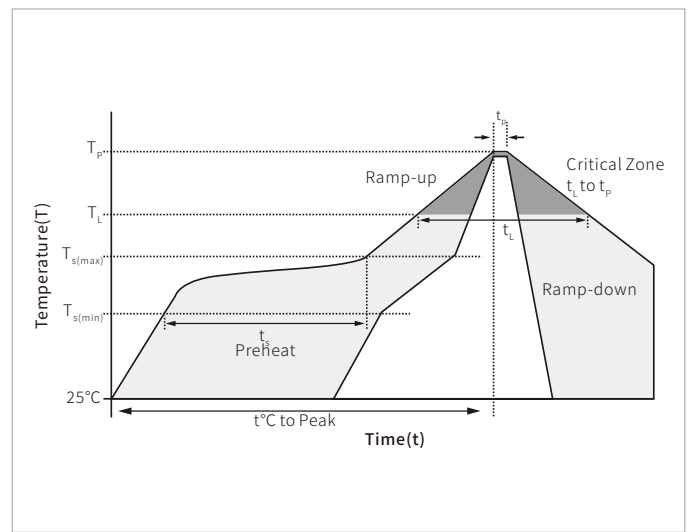
Ref	Outline Dimensions
	Millimeters
A	6.0 $\pm$ 0.2
B	3.2
C	$\Phi$ 6.8
D	8.5 $\pm$ 0.2
E	$\Phi$ 6.0 $\pm$ 0.1
F	8.8
G	1.2
H	2.2
I	1.2
J	6

## SOLDERABILITY TEST

Solderability	
Solder Pot Temperature	Solder Dwell Time
245°C ± 5°C	4~6 seconds

## REFLOW PROFILE

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Min	150°C
	Temperature Max	200°C
	Time(min to max)	60~180 secs
Average ramp up rate (Liquidus)Temp ( $T_L$ ) to peak $T_s$ (max)to $T_L$ - Ramp-up Rate		3°C/second max
Reflow	Temperature ( $T_L$ ) (Liquidus)	217°C
	Time(min to max)( $t_s$ )	60~150 seconds
Peak Temperature ( $T_p$ )		260 °C
Time within 5°C of actual peak Temperature ( $t_p$ )		20~40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature ( $T_p$ )		8 minutes max.
Do not exceed		260°C



## ORDERING INFORMATION

Part Number	Size	QTY/Reel	Reel Size
G3R06B230C	Φ6.0*8.5mm	600PCS	13 "

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